



- The following slides summarise the physics and the Maxwell's...
 - without using equations or difficult maths...

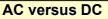
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- leading to some design principles that are easy to visualise and easy to apply...
 - and proven over 30+ years to improve company financial performance...
- and then apply them to an example electronic product

interference technology

The entirety of Real EMC External EMC The real world of 'external' EMC External' EMC Moise margin Vershoot Ringing External' EMC EMC test laboratory measurements

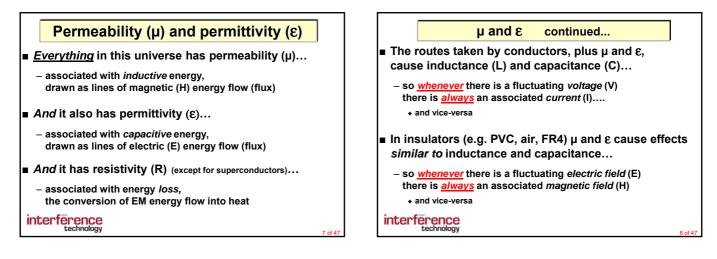


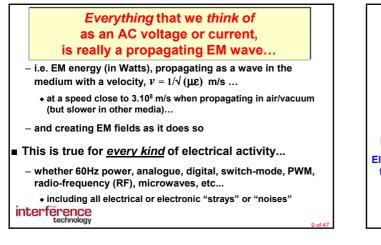
- The following electromagnetic principles apply to all currents, whether they are associated with:
 - electrical power (DC or AC or RF, femtowatts to terawatts)
 - electronic signals (analogue, digital, switch-mode, RF, etc.)
 - noise (in any power supplies or signals)
- DC currents always flow "downhill" from the positive rail to 0V…
 - or uphill from the negative rail...
 - whereas AC and RF currents flow in <u>anv</u> paths, regardless of DC voltage potentials, in <u>any/all</u> directions

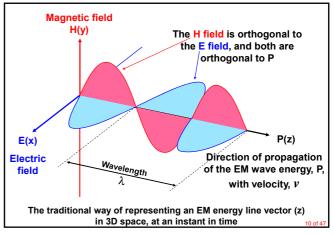
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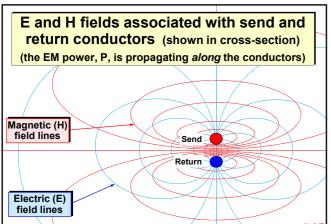






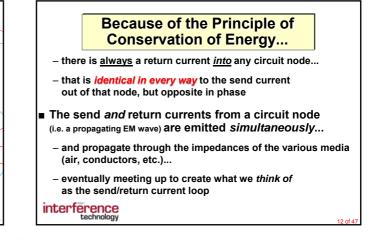






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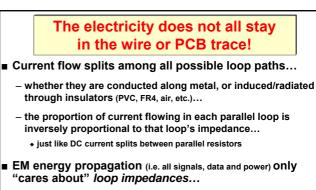




EM power divides amongst all alternative paths according to their loop impedance

- In the "far field" of an EM source, E and H fields experience the "wave impedance": √(μ/ε)...
 - in air or vacuum: 120π Ω (approximately 377Ω)...
 but always a lower Z in other media (PVC, FR4, etc.)
- But in the "near field" of an EM source, the wave Z can be much higher or lower than 377Ω
- And conductors add L, C and R, so can have impedances lower or higher than 377Ω

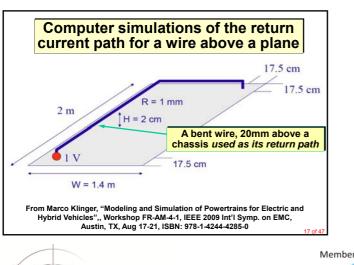
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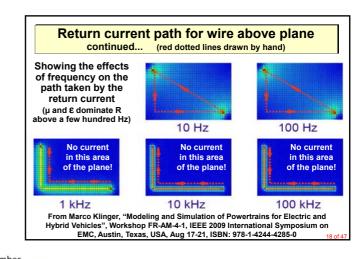
- whether its currents flow in conductors, or insulators

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EMCTLA



All conductors are "accidental antennas"

"Antenna" means that the EM wave energy propagating along conductors...

 that we call electrical/electronic power, signals, noise, etc. and measure as Volts and Amps...

- has a spatial field pattern…
- shaped by the impedances associated with (what we are describing here as...) its send/return current loop...
- which relate to the dimensions and structure of the conductors, their associated dielectrics (insulators), and all of their permeabilities and permittivities

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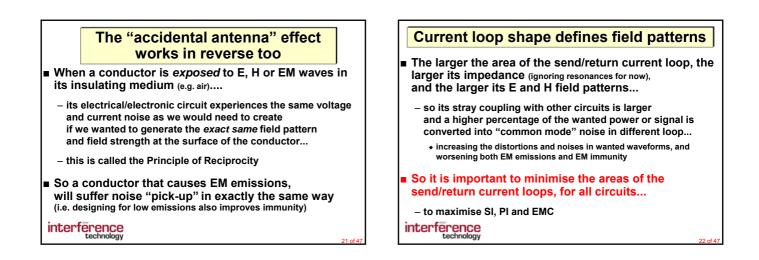
Accidental antennas continued...

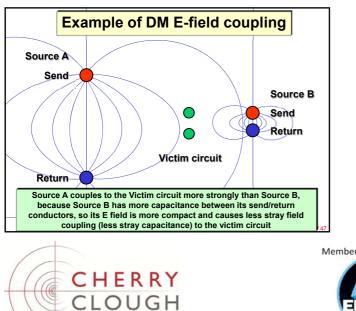
When this EM energy "couples" with other conductors...

- it creates "stray" currents and voltages in their impedances

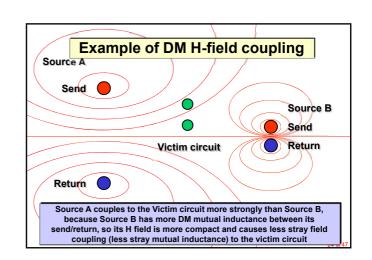
- This can be called "accidental antenna" behaviour...
 - except when we use it to create <u>intentional</u> antennas, for radio and wireless communications...
 - and other uses of radiated EM energy (e.g. medical diathermy, induction heating, etc.)

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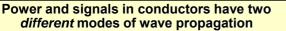
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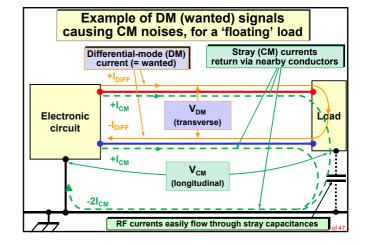


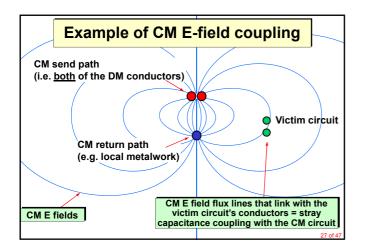


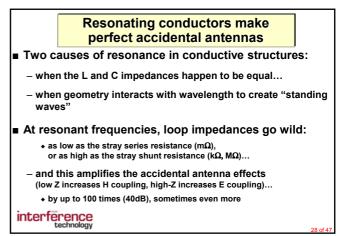
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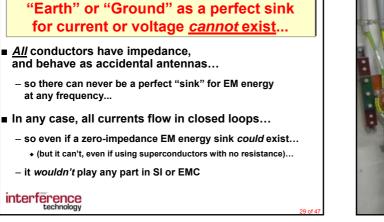


- Differential Mode (also called transverse or metallic mode) caused by the "wanted" power and signals...
- Common Mode (also called longitudinal or antenna mode) caused by stray, leaked, "unwanted" EM energy...
 - when a DM loop's EM fields couple with another conductor
- Some of the EM energy travels as CM current, which also flows in loops...
- almost always the main cause of EM emissions (i.e. the worst "accidental antenna" effects) over 1MHz - 1GHz interference technology

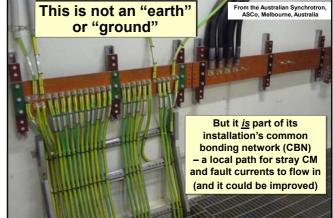










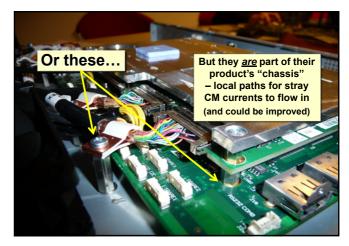


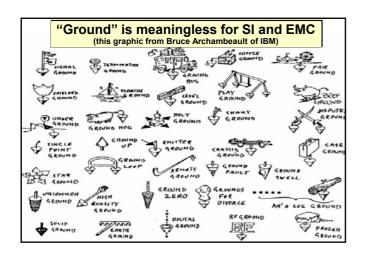


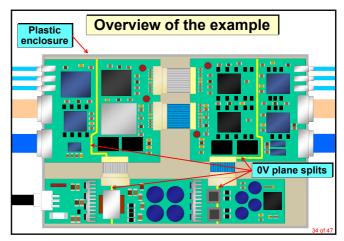


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The assumptions made in its design

Single-point "earthing" or "grounding", using 0V plane splits between (and on) the PCBs...

- assumed to keep devices' circulating return currents confined to certain circuit areas, preventing crosstalk of noise between them (e.g. digital noise in analogue)...
- known to be bad practice, when microprocessors and switchmode converters are used, since 1980 (or earlier)
- Lowest BOM cost assumed to give the most profitable product...
 - known to be incorrect since 2000 (when time to market became the most important issue for a product's profitability)

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I see many designs like this every year... they have poor functional performance at first, especially poor S/N ratios, unreliable software...

- requiring many design iterations to solve, causing project delays, increased costs and reduced profitability
- and they fail EMC tests at first,
 - requiring many design iterations to solve...

The real-life example

- causing more delays and more project costs, requiring filters and shielding that increase BOM cost, reducing profitability even more
- and their higher-than-necessary levels of warranty returns erode profitability even more

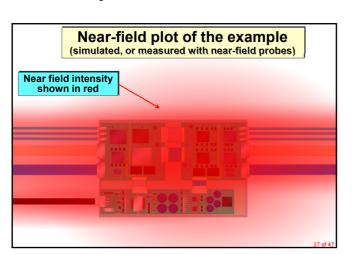
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continued...

7 of 10



 What do such near-fields mean?

 • On the PCB – they are the wanted DM signals...

 - plus DM and CM crosstalk and noise, that cause reduced S/N ratios in analogue circuits, and reduced digital noise margins (unreliable software)

 • In EMC testing...

 - high levels of "far field" emissions, and poor immunity

 • In Real Life...

 - a lower proportion of satisfied customers (hence increased cost of sales) and higher levels of warranty costs

interference

Making improvements

Understanding that <u>all</u> currents (including stray CM "noise" currents) flow in closed loops...

- and that loop shape and area govern field patterns...

- and that current prefers to flow in loops with less Z...
- hence the smallest field patterns, giving the best internal and external EMC...
- means we can make a number of improvements to the circuit design and PCB layout...
- to provide all DM and CM currents with smaller loops...
- which they will naturally take: improving EMC

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Improvement #1 – create an RF Reference Replace the multiple PCBs with a single PCB... – that has a common conductor (almost always at 0V) over its entire area, called the RF Reference...

- a solid, continuous, copper PCB plane, that lies underneath and extends beyond all devices and traces
- which achieves very low impedance (Z)...
 the depends on devices and EMC spec's, but always <<1Ω...
- over the frequency range that must be controlled to avoid causing/suffering EMI...
 - i.e. all of the DM frequencies created in its devices, and all of the frequencies in the operational environment

interference

Improvement #2 – DC supply decoupling

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Design the decoupling between DC power rails and RF Reference to achieve low Z...
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- + the Z needed depends on devices and EMC spec's, but should generally be <<10...
- over the frequency range that needs to be controlled to prevent the product causing/suffering EMI
- Now, AC DM currents in the DC rails can flow in tiny loops very close to the devices that cause them...
 - so they do, and do not flow widely in the RF Reference or power distribution network...
- making small areas of DM near-fields that create little CM interference technology

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Improvement #3 – cable filtering

Add direct bonds or filters to the RF Reference on all traces connected to off-PCB cables...

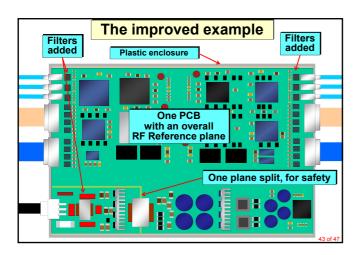
- whatever their electrical/electronic/other purpose
 (including mechanical, hydraulic, pneumatic, etc.)...
- at least using a capacitor to the RF Reference...
 (often making more complex filters by combining capacitors with resistors and/or soft-ferrites, too many details for here)...
- placed where the traces connect to the off-board cables...
- to provide low-Z paths for CM currents that would otherwise "leak" from the PCB into the off-board cables...
- \bullet The Z depends on devices and EMC spec's, but should be <<1 $\!\Omega$

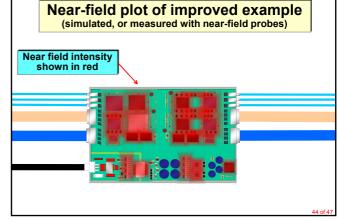
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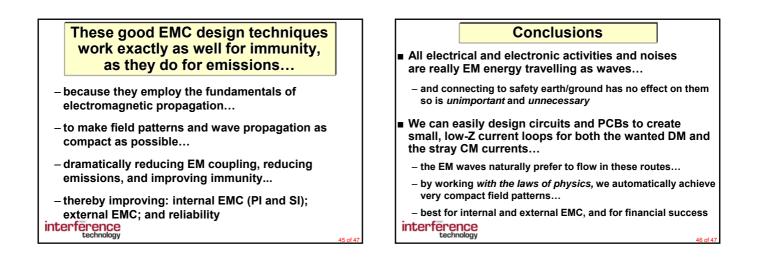


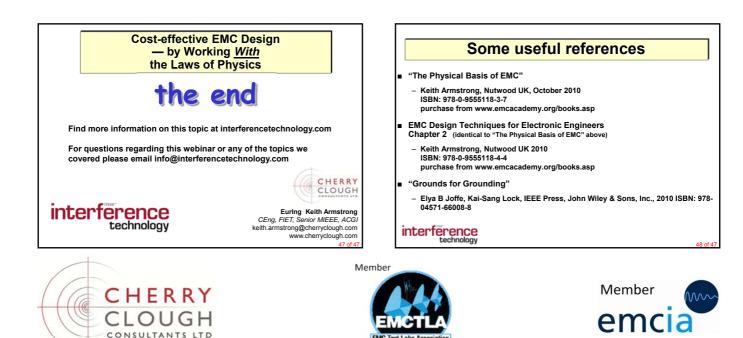


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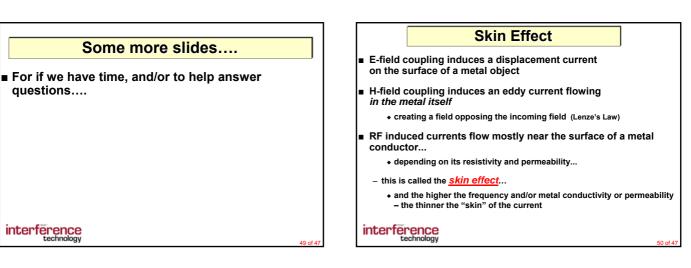


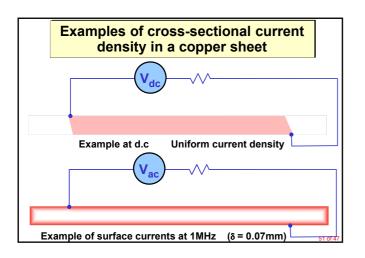




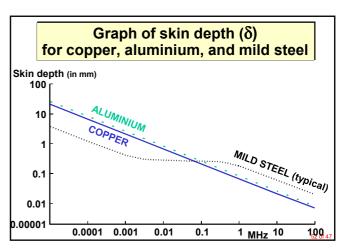


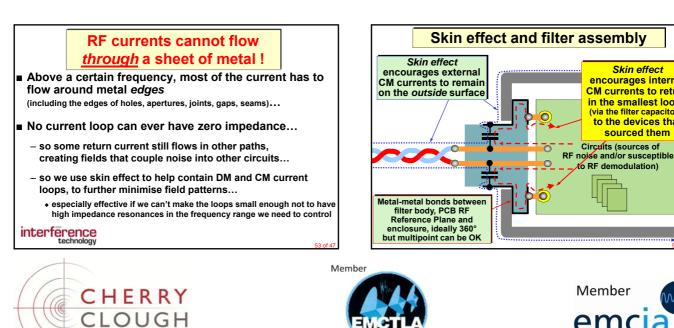
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Skin effect

encourages internal

CM currents to return

in the smallest loops (via the filter capacitors) to the devices that

sourced them

RF demodulation)

Improvement #4 – cable shielding

- Add shielding to <u>all</u> unfiltered and unbonded off-board conductors...
 - to contain the CM currents that would otherwise "leak" out of (or into) the conductors as EM fields
 - shielding can also be used in addition to filtering
- Use 360° shielding throughout...
 - including the shields' connections to the RF Reference
 too many details to go into here, except don't use pigtails to connect cable shields

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Pigtails are very bad for cable shields! Example of measurements on 25-way subminiature D-type, developed from page 27 of "Analysis of Electromagnetic Shielding of Cables and Connectors (keeping currents/voltages where they belong)", Lothar O. (Bud) Hoeft, PhD, IEEE, 2002 $Z_{T Ohms}_{100}$ [']Pigtail' braid termination 6000 times worse (-75dB) at 100MHz, than 360° braid termination 10 Diecast metal backshell with 360° braid termination 1 0 1 0.01 0.001 0.0001 0.001 0.01 0.1 1 10 MHz 100 Lower Z_T = better shielding effectiveness (SE)

Improvement #5 – PCB shielding

- The enclosure can be converted from plastic to metal (or metallised)...
 - and RF-bonded to the PCB's RF Reference
- Alternatively, shielding can be carried out at PCB level...
- by electrically bonding metal (or metallised) boxes onto the RF Reference
- Either will help contain EM fields that have not been sufficiently constrained...
 - by devices and design of circuits, decoupling and PCB

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